## ABSTRACT OF THE DISCLOSURE

Disclosed is a single crystal substrate and a cutting method thereof.

single crystal substrate includes a langasite substrate with a SAW propagation surface; and input and output IDTs having electrodes on the surface for launching and/or detecting surface acoustic waves, wherein a direction of surface wave propagation is parallel to an X'-axis, and the substrate further has an Z'-axis perpendicular to the surface and a Y'-axis parallel the to surface perpendicular to the X'-axis, the langasite substrate having a crystal orientation defined by modified axes X, Y and Z, the relative orientation of axes X', Y' and Z' being defined by Euler angles  $\phi$ ,  $\theta$  and  $\psi$ , in which  $\phi$  is in a range of  $8^{\circ} \leq \phi$  $\leq$  25°,  $\theta$  is in a range of 15°  $\leq$   $\theta$   $\leq$  30°, and  $\psi$  is in a range of  $55^{\circ} \le \psi \le 85^{\circ}$ .

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